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Printed Circuits Handbook

Sixth Edition

- Lead-free PCB design and manufacturing techniques
- Lead-free materials
- Lead-free reliability models
- High-Density Interconnection (HDI) best practices

Clyde F. Coombs, Jr.

PRINTED CIRCUITS HANDBOOK

To Ann

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PRINTED CIRCUITS HANDBOOK

Clyde F. Coombs, Jr. Editor-in-Chief

Sixth Edition

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